

## **NCE N-Channel Super Trench Power MOSFET**

### **Description**

The series of devices uses Super Trench technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{\text{DS}(\text{ON})}$  and  $Q_{\text{g}}.$  This device is ideal for high-frequency switching and synchronous rectification.

### **Application**

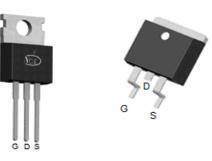
- ●DC/DC Converter
- ■Ideal for high-frequency switching and synchronous rectification

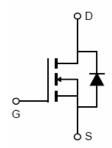
#### **General Features**

- ●V<sub>DS</sub> =150V,I<sub>D</sub> =70A  $R_{DS(ON)}$ =13.5m $\Omega$  (typical) @  $V_{GS}$ =10V
- ●Excellent gate charge x R<sub>DS(on)</sub> product(FOM)
- Very low on-resistance R<sub>DS(on)</sub>
- ●175 °C operating temperature
- Pb-free lead plating

**100% UIS TESTED!** 100% AVds TESTED!

**TO-220 TO-263** 





**Schematic Diagram** 

## **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP1570	NCEP1570	TO-220			
NCEP1570D	NCEP1570D	TO-263	-	-	-

### Absolute Maximum Ratings (T<sub>A</sub>=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	150	V
Gate-Source Voltage	$V_{GS}$	±20	V
Drain Current-Continuous	I <sub>D</sub>	70	А
Drain Current-Continuous(T <sub>C</sub> =100°C)	I <sub>D</sub> (100℃)	49	Α
Pulsed Drain Current	I <sub>DM</sub>	280	Α
Maximum Power Dissipation	P <sub>D</sub>	200	W
Derating factor		1.33	W/℃
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	672	mJ
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 175	$^{\circ}$

# http://www.ncepower.com

# NCEP1570,NCEP1570D

### **Thermal Characteristic**

Thermal Résistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{ heta JC}$	0.75	°C/W	
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**Electrical Characteristics (T<sub>A</sub>=25 ℃ unless otherwise noted)** 

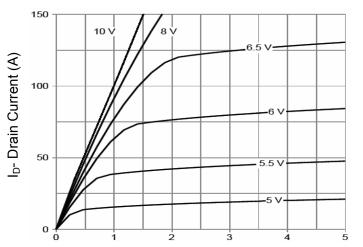
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	·					
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	150	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =150V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	2.0	3.1	4.0	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =35A	-	13.5	15	mΩ
Forward Transconductance	<b>g</b> FS	$V_{DS}$ =5 $V$ , $I_D$ =35 $A$	-	58	-	S
Dynamic Characteristics (Note4)	<u>.</u>		•	•		
Input Capacitance	C <sub>lss</sub>	\/ 75\/\/ 0\/	-	2000	-	PF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =75V,V <sub>GS</sub> =0V, — F=1.0MHz —		280	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>			16	-	PF
Switching Characteristics (Note 4)			•			
Turn-on Delay Time	t <sub>d(on)</sub>		-	12.5	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =75V, $I_{D}$ =35A	-	3.8	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10 $V$ , $R_{G}$ =3 $\Omega$	-	14	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	3.5	-	nS
Total Gate Charge	Qg	\/ -75\/  -25A	-	35	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =75V, $I_{D}$ =35A, $V_{GS}$ =10V	-	11.8	-	nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V	-	9.9	-	nC
Drain-Source Diode Characteristics	<u>.</u>		•	•		
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =35A	-	-	1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>		-	-	70	Α
Reverse Recovery Time	t <sub>rr</sub>	$T_J = 25^{\circ}C$ , $I_F = 35A$	-	47	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	65	-	nC

### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec. The value of R<sub>BJA</sub> is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> =25° C. the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- 5. E<sub>AS</sub> condition : Tj=25  $^{\circ}\text{C}$  ,V<sub>DD</sub>=50V,V<sub>G</sub>=10V,L=0.5mH,Rg=25 $\Omega$

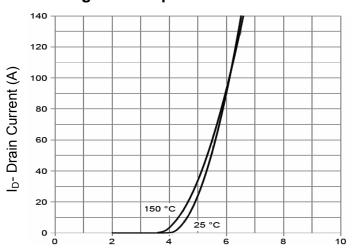


### **Typical Electrical and Thermal Characteristics**



Vds Drain-Source Voltage (V)

**Figure 1 Output Characteristics** 



Vgs Gate-Source Voltage (V)

**Figure 2 Transfer Characteristics** 

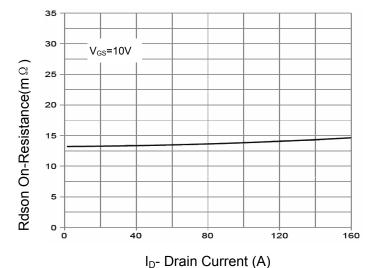
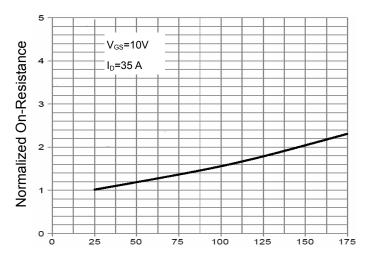
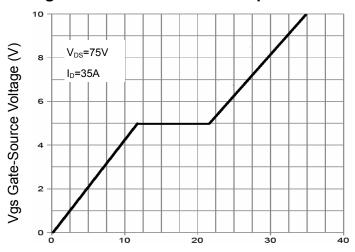


Figure 3 Rdson- Drain Current

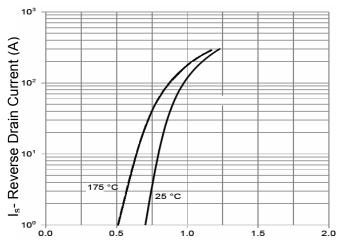


T<sub>J</sub>-Junction Temperature(°C)

**Figure 4 Rdson-Junction Temperature** 



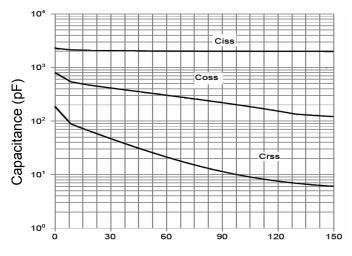
Qg Gate Charge (nC)
Figure 5 Gate Charge



Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward



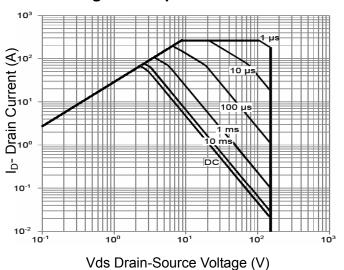


Power Dissipation (W) 160 120 80 40 100 200

Vds Drain-Source Voltage (V)

Figure 7 Capacitance vs Vds

 $T_J$ -Junction Temperature( $^{\circ}$ C) Figure 9 Power De-rating



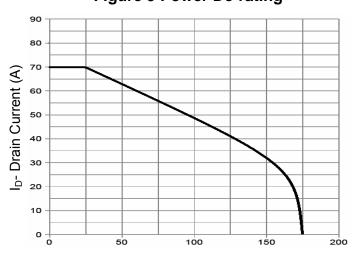
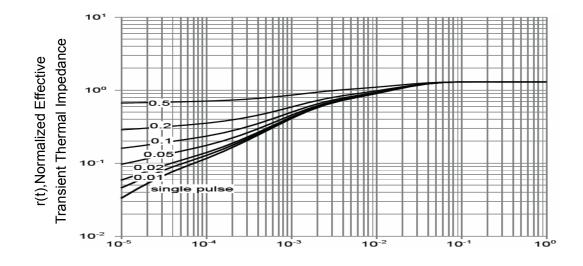


Figure 8 Safe Operation Area

 $T_J$ -Junction Temperature ( $^{\circ}$ C) Figure 10 Current De-rating



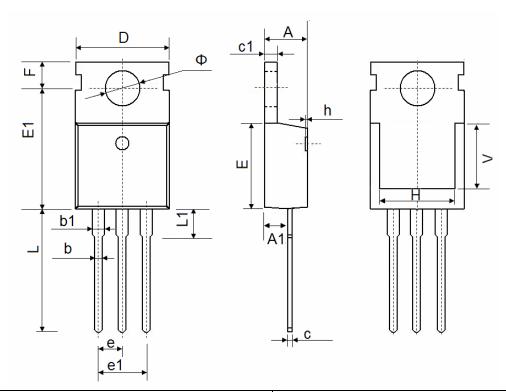
200

Square Wave Pluse Duration(sec)

**Figure 11 Normalized Maximum Transient Thermal Impedance** 



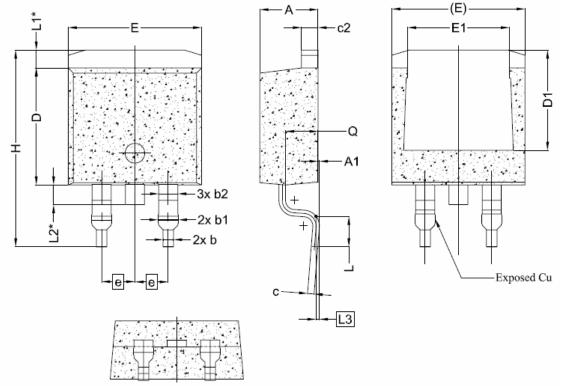
# **TO-220-3L Package Information**



Cumbal	Dimensions In Millimeters		Dimension	s In Inches
Symbol	Min.	Max.	Min.	Max.
А	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
С	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
Е	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
е	2.540	2.540 TYP. 0.100 TY		TYP.
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
Н	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	6.900	REF. 0.276 REF.		REF.
Ф	3.400	3.800	0.134	0.150



# **TO-263-2L Package Information**



Symbol	Dimensions In Millimeters				
Symbol	Min.	Nom.	Max.		
А	4.24	4.44	4.64		
A1	0.00	0.10	0.25		
b	0.70	0.80	0.90		
b1	1.20	1.55	1.75		
b2	1.20	1.45	1.70		
С	0.40	0.50	0.60		
c2	1.15	1.27	1.40		
D	8.82	8.92	9.02		
D1	6.86	7.65	-		
E	9.96	9.96 10.16			
E1	6.89 7.77		7.89		
е	2.54BSC				
Н	14.61	14.61 15.00			
L	1.78	2.32	2.79		
L1	1.36 REF.				
L2	1.50 REF.				
L3	0.25 BSC				
Q	2.30	2.48	2.70		





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